Supplier Name:	**Texas Instruments Inc. (DUNS# 00-732-1904)**
Contact Info:	ti.com/support
Form/Declaration Type:	**Distribute - RoHS, REACH, Green and IEC 62474 DB**
Created on:	**04/10/2025**

Details for "DP83848KSQ/NOPB"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow
DP83848KSQ/NOPB	SN	Level-2-260C-1 YEAR

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information (click on the column headers for details of the stated compliance st

RoHS	REACH	Green
Yes	Yes	Yes

Component Information

Component	Substance	CAS Number
Bond Wire		
Aluminum and Its Alloys	Aluminum	7429-90-5
Copper and Its Alloys	Copper	7440-50-8
Copper and Its Alloys	Iron	7439-89-6
Not Categorized	Proprietary Materials	
Precious Metals	Gold	7440-57-5
Precious Metals	Palladium	7440-05-3
Precious Metals	Silver	7440-22-4
Sub-Total		
Die Attach Adhesive		
Precious Metals	Silver	7440-22-4
Thermoplastics	Epoxy	85954-11-6
Sub-Total		
Lead Frame		
Copper and Its Alloys	Copper	7440-50-8
Copper and Its Alloys	Iron	7439-89-6
Copper and Its Alloys	Phosphorus	7723-14-0
Other Nonferrous Metals and Alloys	Lead	7439-92-1
Precious Metals	Silver	7440-22-4

Sub-Total		
Lead Frame Plating		
Other Nonferrous Metals and Alloys	Tin	7440-31-5
Sub-Total		
Mold Compound		
Other Inorganic Materials	Fused Silica	60676-86-0
Other Organic Materials	Carbon Black	1333-86-4
Thermoplastics	Epoxy	85954-11-6
Sub-Total		
Semiconductor Device		
Ceramics / Glass	Doped Silicon	7440-21-3
Sub-Total		
Total		

Important Note

The ppm values are at the **homogeneous material** level and are maximum concentration values.
The amount (mg) represents the maximum total amount of each substance within the component.
Refer to the following document for additional information:
Environmental FAQs

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more tha
check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology: Refer the following document for an overview of the TI approach to providing m
Environmental FAQs

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of
products designated to be RoHS compliant, with or without claiming exemptions fully meet the latest EU Rol

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, an
analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be pro
For additional information, click here to contact TI customer support.

Signature: (click here for TI's complete RoHS position statement and signed certificate)
Signature: (click here for TI's complete REACH position statement and signed certificate)

Vice President, Worldwide SC Quality
For additional environmental position statements, please go to www.ti.com/ecoinfo

Created on: 04/10/2025

Assembly site	Package | Pins	Package body size (mm)
Texas Instruments Electronics	RTA | 40	6 x 6 x 0.75

atus)

IEC 62474 DB
Yes

	Homogeneous Material Level	
Amount (mg)	Percentage %	ppm
0.000001	0.000381	4
0.249043	94.96469	949647
0.000002	0.000763	8
0.000029	0.011058	111
0.002783	1.061209	10612
0.010387	3.960755	39608
0.000003	0.001144	11
0.262248	**100**	**1000000**
0.365842	75.000051	750001
0.121947	24.999949	249999
0.487789	**100**	**1000000**
44.768232	96.7	967000
1.203696	2.6	26000
0.069444	0.15	1500
0.00463	0.010001	100
0.249998	0.539999	5400

46.296	**100**	**1000000**
0.1	100	1000000
0.1	**100**	**1000000**
35.158082	90.499999	905000
0.194244	0.500001	5000
3.496384	9	90000
38.84871	**100**	**1000000**
1.226377	100	1000000
1.226377	**100**	**1000000**
87.221124		

n one TI part number. This is due to two or more users (EMSIs or subcontractors) using th

aterial content compliance data.

f their knowledge based on material information provided by its suppliers and their combi
HS Directive requirements along with other legislation as seen in the former JIG-101 list th

d continues to take, reasonably diligent steps to provide any required or available informa
prietary, and thus certain information may not be available for release by TI. The material

Total device mass (mg)*
87.2

Component Level	
Percentage %	ppm
0.000001	0
0.285531	2855
0.000002	0
0.000033	0
0.003191	32
0.011909	119
0.000003	0
0.30067	**3007**
0.419442	4194
0.139814	1398
0.559256	**5593**
51.327282	513273
1.380051	13801
0.079618	796
0.005308	53
0.286626	2866

53.078885	**530789**
0.114651	1147
0.114651	**1147**
40.309137	403091
0.222703	2227
4.008644	40086
44.540483	**445405**
1.406055	14061
1.406055	**14061**
100	1000000

e same CPN for different TI part numbers. If this occurs, please

nation into finished IC packaged products. TI semiconductor
ıat has been transferred to the IEC 62474 database.

ıtion. TI may not have conducted destructive testing or chemical
content information is provided by TI "as is."